

ABSTRACT

Provided is a semiconductor processing pressure sensitive adhesive sheet including a substrate having thereon an intermediate layer and a pressure sensitive adhesive layer in this order, the semiconductor processing pressure sensitive adhesive sheet satisfying the following (a) and (b):

(a) a loss tangent of the intermediate layer at 50°C as measured at a frequency of 1 Hz is 1.0 or more, and

(b) a ratio $[A/I]$ of a storage elastic modulus A of the pressure sensitive adhesive layer and a storage elastic modulus I of the intermediate layer at 50°C as measured at a frequency of 1 Hz is 1.8 or less.